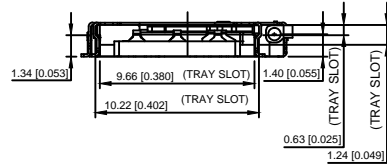


XKB Connectivity  
**RECOMMEND P.C.B LAYOUT**  
 (General tolerance ±0.05)

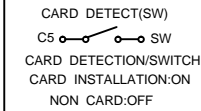


XKB Connectivity

**NOTE:**

- 1.材料 Material:
  - 1-1 胶壳 Housing:High Temperature Thermoplastic(LCP S475)Color Black UL 94V-0
  - 1-2 触点 Contact:Phosphor Bronze(C5210R-H,T=0.10±0.01mm)
  - 1-3 外壳 Cover:SUS301-HT=0.15 ± 0.03mm
- 2.电镀 Plating:
  - 2-1 接触端子 Contact terminal:
    - 接触电阻 Contact area: Gold 1u" Min.
    - 焊接区 Solder area: Gold 0.8u"Min
    - 底镀 Underplating:Ni overall 50U"Min.
  - 2-2 外壳 Cover:
    - 底镀 Underplating: Ni overall 30U"Min.
    - 焊接区 Solder area: Gold 0.8u"Min.
- 3.规格 Specification:
  - 3-1.额定电流 Current Rating :0.5A max.
  - 3-2.接触电阻 Contact Resistance:50 mOhms max
  - 3-3.绝缘电阻 Insulation Resistance:1000 MOhms min./500VDC
  - 3-4.耐电压 Dielectric Withstanding Voltage:500 V AC/1minute
  - 3-5.工作温度 Operating Temperature:-25 ℃ to+85 ℃
  - 3-6.插拔次数 Mating Cycles:5000 Insertions
- 4.Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC
- 5.Recommending A Metal More Than 0.15mm Thick.  
 Please Confirm Solderability,If Use A Metal Mask Less Than 0.15mm Thick.

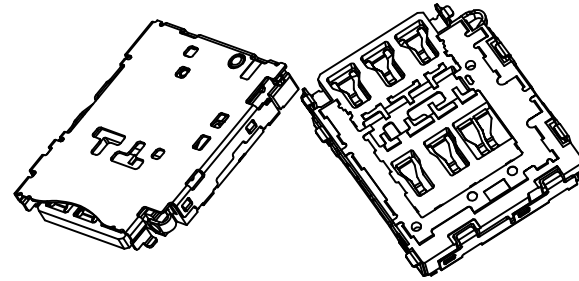
**COMPOSITION OF DETECTION**



XKB Connectivity

**SIM Card Pin Assignments**

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



DSND		DATE		SCALE: N/A	MODEL TYPE: SIM CARD CONN
DWN		DATE		VIEW:	PART NO.:
CHKD		DATE		UNIT: mm/in	DWG NO.:
APPD		DATE		SIZE: A4	XKNANO-1131-1
				XKB INDUSTRIAL PRECISION CO.,LIMITED	WEIGHT 1.0g
					SHEET 1/1
					REVISION A0

ΔX					ANGLAR	±5°
ΔX					L ≤ 4	±0.2
ΔX					4 < L ≤ 16	±0.3
MARK	DESCRIPTION	DATE	REVISED	APPROVED	16 < L ≤ 63	±0.4
					L > 63	±0.5
REVISIONS					UNSPECIFIED TOLERANCES	
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